Thermal Potting Compound

Features:

1. Good flowability and self-leveling, with low-density stability that resists settling.
2. High temperature tolerance, maintaining durability without cracking in extreme conditions.
3. Enhances internal strength after potting, protecting components while providing thermal conductivity and electrical insulation.

Applications:
Securing PCBs within casings, inverters, car chargers, and automotive power modules.

Model	Thermal Conductivity W/m·K	Viscosity after Mixed, cPs	Hardness After Curing, Shore A	DielectricStrength, kV/mm,AC
JSUS-5201-00	0.8	2000~3000	45±10	＞2.0
JSUS-5201-10	1.0	2500~3000	20±5	＞2.0
JSUS-5201-15	1.5	4000~4500	45±5	＞2.5
JSUS-5201-20	2.0	6000~6500	20±5	＞2.5
JSUS-5201-25	2.5	8000~8500	20±5	＞4.0
JSUS-5201-30	3.0	22000~23000	60±5	＞4.5
JSUS-5201-35	3.5	24000~25000	60±5	＞5.0